

ABSTRACT

An object of the present invention is to provide a sealing sheet for a semiconductor element and a production method that enable production of a semiconductor device in which the information given by marking can be satisfactorily visually recognized. An aspect of the present invention relates to the sealing sheet for a semiconductor element, having a release film having a surface smoothness (Ra) of 0.1 to 0.5 μm and an average distance of unevenness (RSm) of 90 to 125 μm in surface conditions and a sealing material layer arranged on the release film.